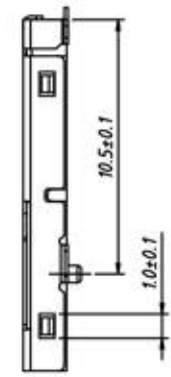
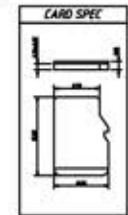
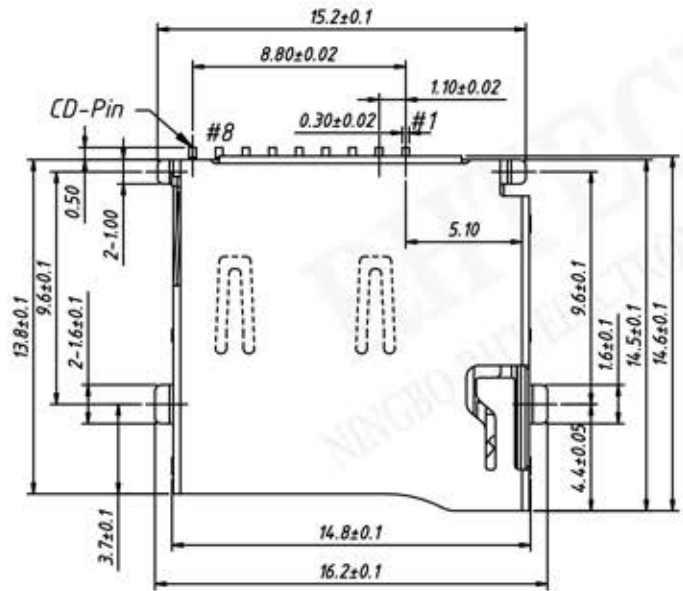
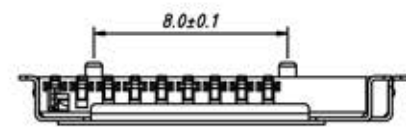
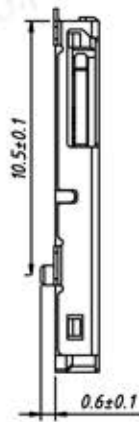
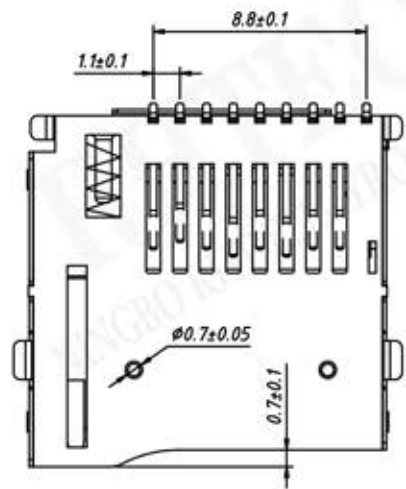
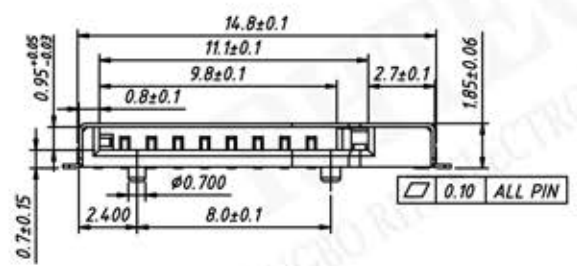


P/N: RE-C-TF-003C-H1.9-R



Material:
 Insulator: High Temperature Thermoplastic, LCP, UL94V-0.
 Contact: Copper Alloy T=0.15, Plated 50u" Ni Overall. Plated Au Selective Contact Area Plated 30u"-70u" Sn Over Ni On Solder Area.
 Shell: T=0.15, Plated 30u" Ni Overall min. Plated 0.5u" Au Selective Contact Area.

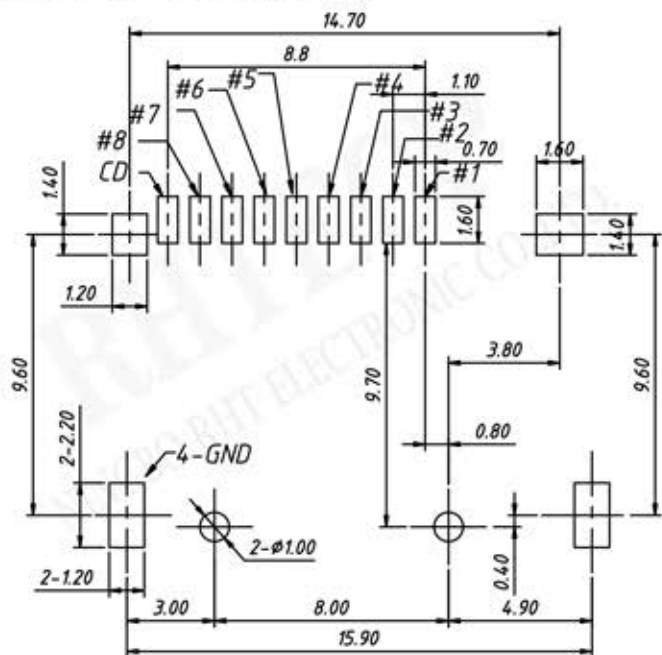
Electrical:
 Current Rating: 0.5mA AC/DC amx.
 Voltage Rating: 125V AC/DC
 Ambient Temperature Range: -25°C ~ +85°C
 Storage Temperature Range: -25°C ~ +85°C
 Ambient Humidity Range: 95% R.H. Max.
 Contact Resistance: 100mΩ Max.
 Insulation Resistance: 1000MΩ Min./500VDC
 Mating Cycles: 5000 Insertions.
 Peak temperature: 260°C ±0.5°C



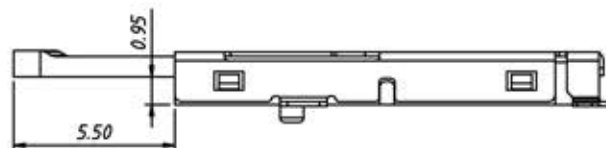
UNITS:mm	SHEET SIZE:A4		SCALE: ---
> 0 ~ 3	> 3 ~ 18	> 18 ~ 50	> 50 ~ 120
± 0.12	± 0.15	± 0.3	± 0.5

P/N: RE-C-TF-003C-H1.9-R

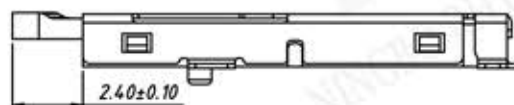
T-Flash Card Insert Drawing:



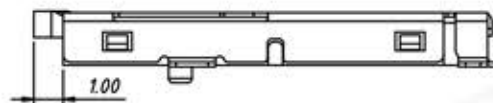
PIN NO.	PIN ASSIGNMENT
1 #	DAT2
2 #	CD/DAT3
3 #	CMD
4 #	VDD
5 #	CLK
6 #	VSS
7 #	DAT0
8 #	DAT1
9 #	CD



Micro SD Card-Un Lock



Micro SD Card-Lock



Micro SD Card-Push

